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-Mihai Telescu

University of Brest, Brest (FRA)

-Dries Vande Ginste

Ghent University, Gent (BEL)

IMPORTANT DATES

- Full Paper Submission: Dec 20th, 2024
- Notification of Acceptance: Jan 31st, 2025
- Final Paper Submission: Mar 14th, 2025
- Early Bird Registration: Mar 14th, 2025
- Sponsors Registration: Mar 31st, 2025

Standing for almost three decades, the IEEE Workshop on Signal and Power Integrity (SPI) has evolved into a noteworthy forum of exchange on all aspects of Signal and Power Integrity, comprising the latest research and developments on design, characterization, modeling, simulation and testing at chip, package, board, and system level. The workshop brings together developers and researchers from acade-

mia and industry in order to encourage cooperation, and the technical program will

include both oral and poster sessions, while several prominent experts will be giving keynotes and tutorials on areas of emerging interest. The 29th Edition of SPI will be held as an in-person event during May 11-14, 2025, in Gaeta, Italy.

Follow us on LinkedIn and feel free to look into our website for further information about SPI 2025, as well as broadcast the workshop in your institution and to your fellow colleagues and students. It is a pleasure to invite you all to the 29th IEEE Workshop on Signal and Power Integrity and we look forward to your contribution and participation!

CALL FOR PAPERS

Original and unpublished contributions on all aspects of Signal and Power Integrity are welcomed, related to the following topics of interest:

- Modeling and simulation for SI/PI
- Coupled signal and power integrity analysis
- Noise reduction and equalization techniques
- · High-speed link design and modeling
- · Power distribution networks
- · RF/microwave/mm-wave systems and packaging solutions
- · Antennas-in-package and antennas-on-
- 3D IC and packages (TSV/SiP/SoC)

- · Electromagnetic theory and modeling
- · Transmission line theory and modeling
- Macromodeling, reduced order models
- · Electromagnetic compatibility
- Design methodology/flow measurements
- · Jitter and noise modeling
- Stochastic/sensitivity analysis
- · Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- · Optical interconnects
- Nano-interconnects and nano-structures Al in electronics design

SPONSORSHIPS

Companies can actively support SPI 2025: don't miss this key opportunity to promote your products and services to our participants, enhancing your visibility and reputation on Signal and Power Integrity expertise!

Registration for Sponsors is open!



